

May 2001

# FQT4N25

## 250V N-Channel MOSFET

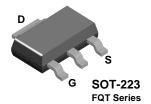
## **General Description**

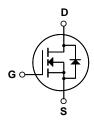
These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switching DC/DC converters, switch mode power supply.

#### **Features**

- 0.83A, 250V,  $R_{DS(on)}$  = 1.75 $\Omega$  @V<sub>GS</sub> = 10 V Low gate charge ( typical 4.3 nC)
- Low Crss (typical 4.8 pF)
- Fast switching
- · Improved dv/dt capability





# Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter		FQT4N25	Units
V <sub>DSS</sub>	Drain-Source Voltage		250	V
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> = 25	°C)	0.83	Α
	- Continuous (T <sub>C</sub> = 70°C)		0.66	Α
I <sub>DM</sub>	Drain Current - Pulsed	(Note 1)	3.3	Α
V <sub>GSS</sub>	Gate-Source Voltage		± 30	V
E <sub>AS</sub>	Single Pulsed Avalanche Energy	(Note 2)	52	mJ
I <sub>AR</sub>	Avalanche Current	(Note 1)	0.83	А
E <sub>AR</sub>	Repetitive Avalanche Energy	(Note 1)	0.25	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	5.5	V/ns
$P_D$	Power Dissipation (T <sub>C</sub> = 25°C)		2.5	W
	- Derate above 25°C		0.02	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150	°C
T <sub>L</sub>	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C

## **Thermal Characteristics**

Symbol	Parameter	Тур	Max	Units
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient *		50	°C/W

<sup>\*</sup> When mounted on the minimum pad size recommended (PCB Mount)

Symbol	Parameter	Test Conditions		Тур	Max	Units
Off Cha	racteristics					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V, } I_{D} = 250 \mu\text{A}$	250			V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, Referenced to 25°	C	0.22		V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 250 V, V <sub>GS</sub> = 0 V			1	μА
		V <sub>DS</sub> = 200 V, T <sub>C</sub> = 125°C			10	μА
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0 V			100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
On Cha	racteristics					
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	3.0		5.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 0.415 A		1.38	1.75	Ω
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 50 V, I <sub>D</sub> = 0.415 A (Note 4)		1.28		S
<b>Dynam</b> i C <sub>iss</sub>	ic Characteristics Input Capacitance	V 05 V V 0 V		155	200	pF
C <sub>oss</sub>	Output Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0  MHz		35	45	рF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 = 1.0 WHZ		4.8	6.5	pF
	'					
	ng Characteristics			T	T	ı
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 125 V, I <sub>D</sub> = 3.6 A,		6.8	25	ns
t <sub>r</sub>	Turn-On Rise Time	$R_G = 25 \Omega$		45	100	ns
t <sub>d(off)</sub>	Turn-Off Delay Time			6.4	25	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note 4,	5)	22	55	ns
$Q_g$	Total Gate Charge	$V_{DS} = 200 \text{ V}, I_{D} = 3.6 \text{ A},$		4.3	5.6	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>GS</sub> = 10 V		1.3		nC
$Q_{gd}$	Gate-Drain Charge	(Note 4,	5)	2.1		nC
Drain-S	ource Diode Characteristics a	nd Maximum Ratings				
I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current				0.83	Α
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode F	n-Source Diode Forward Current			3.3	Α
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 0.83 \text{ A}$			1.5	V
t <sub>rr</sub>	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_{S} = 3.6 \text{ A},$		110		ns
Q <sub>rr</sub>	Reverse Recovery Charge	$dI_F / dt = 100 A/\mu s$ (Note	4)	0.35		μС

**Notes:**1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 120mH, I<sub>AS</sub> = 0.83A, V<sub>DD</sub> = 50V, R<sub>G</sub> = 25 Ω, Starting T<sub>J</sub> = 25°C 3. I<sub>SD</sub>  $\leq$  3.6A, di/dt  $\leq$  300A/μs, V<sub>DD</sub>  $\leq$  BV<sub>DSS</sub>, Starting T<sub>J</sub> = 25°C 4. Pulse Test : Pulse width  $\leq$  300μs, Duty cycle  $\leq$  2% 5. Essentially independent of operating temperature

# **Typical Characteristics**

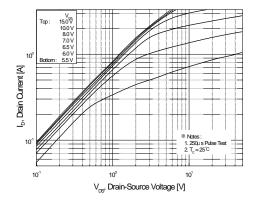


Figure 1. On-Region Characteristics

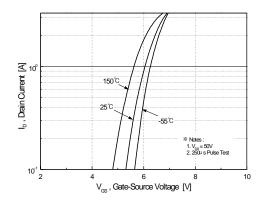


Figure 2. Transfer Characteristics

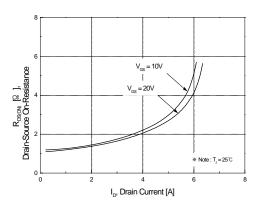


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

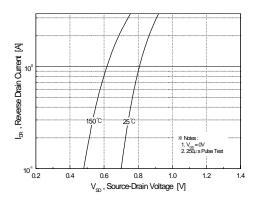


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

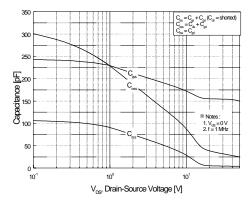


Figure 5. Capacitance Characteristics

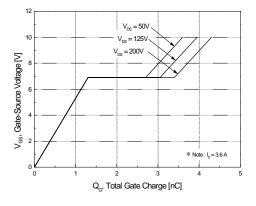
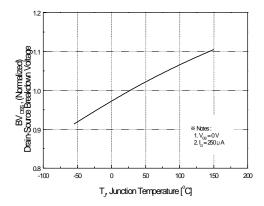


Figure 6. Gate Charge Characteristics

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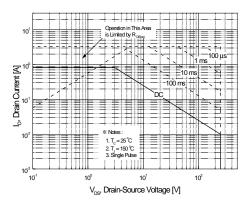
# Typical Characteristics (Continued)



2.5 (000) 2.0 (0

Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



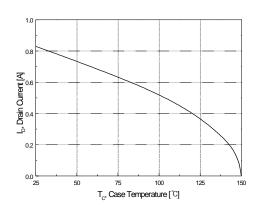


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

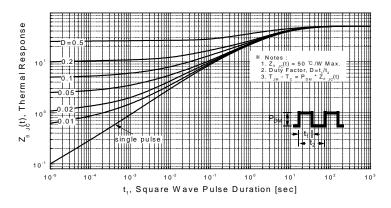
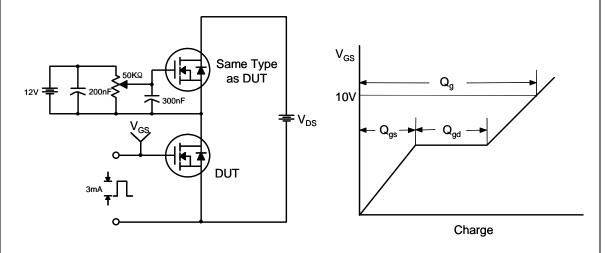


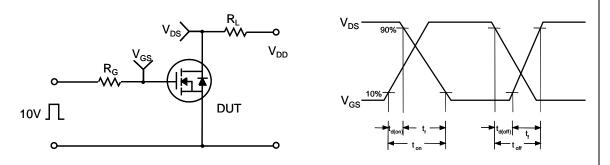
Figure 11. Transient Thermal Response Curve

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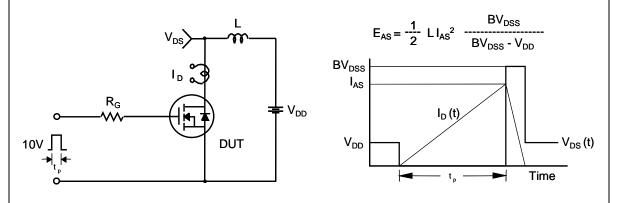
## **Gate Charge Test Circuit & Waveform**



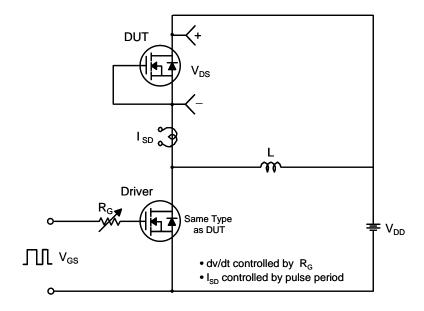
## **Resistive Switching Test Circuit & Waveforms**

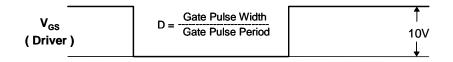


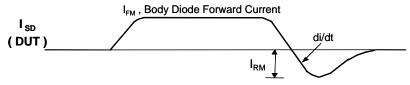
## **Unclamped Inductive Switching Test Circuit & Waveforms**



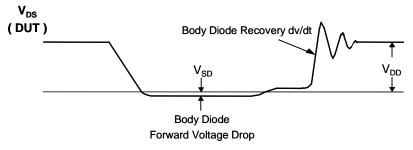
### Peak Diode Recovery dv/dt Test Circuit & Waveforms





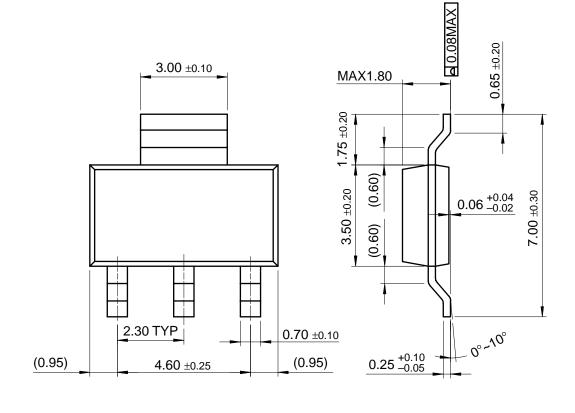


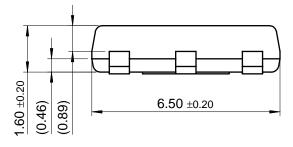
Body Diode Reverse Current



# **Package Dimensions**

# SOT-223





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